

Notice of References Cited	Application/Control No. 10/566,571	Applicant(s)/Patent Under Reexamination SAWAI, MASAYOSHI	
	Examiner Tung S. Lau	Art Unit 2863	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	D.S. Liu, Study of wire bonding looping formation in the electronic packaging process using three-dimensional finite element method, October 22, 2002, page 263-286
	V	http://mw1.merriam-webster.com/dictionary/tangent , page 1
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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